

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Appl. No. : **10/809,182** Confirmation No. **6820**  
Applicant(s) : **UMENO, Kuniharu et al.**  
Filed : **03/25/2004**  
TC/A.U. : **1712**  
Examiner : **Robert E. Sellers**  
Title : **Resin Composition for Encapsulating Semiconductor Chip and  
Semiconductor Device Therewith**

Docket No. : **033036.076**  
Customer No. : **25461**

**MAIL STOP AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450  
Sir:

**AMENDMENT**

This is in response to the Office Action of June 28, 2006. Please amend the above-identified application as follows:

**Amendments to the specification** are reflected beginning on page 2.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 4 of this paper.

**Remarks/Arguments** begin on page 9 of this paper.